

IR-1773 (2-2498)

**POWER SEMICONDUCTOR DIE
ATTACH PROCESS USING ADHESIVE FILM**

ABSTRACT OF THE DISCLOSURE

A large area adhesive film is attached to a semiconductor wafer containing a large number of identical structures. The film and wafer are then simultaneously singulated and the individual die with film thereon are then placed atop a lead frame and the film is completely cured to adhere the semiconductor die to the lead frame. Plural die can be mounted side-by-side on a common substrate, or one die can be mounted atop a second die which is on the substrate.